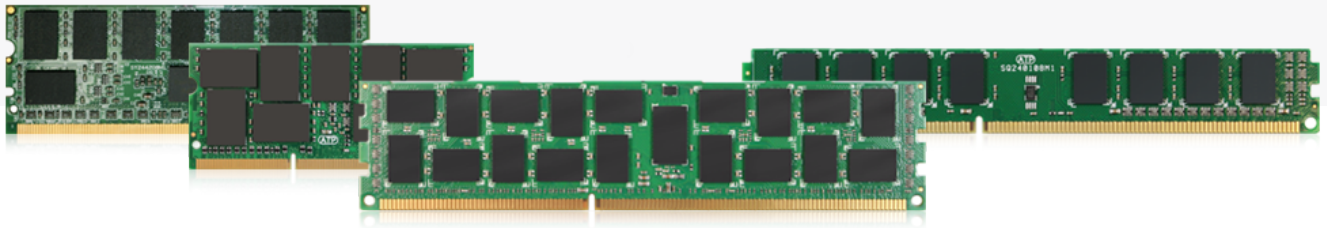




DDR3

The Global Leader in Specialized Storage and Memory Solutions



KEY FEATURES

- Density: 1 GB to 16 GB
- Chipkill support
- Fly-by command/address/control bus with on-DIMM termination
- Higher bandwidth performance, effectively up to 1866 MT/s
- Better performance at low power; 1.5V (Normal) and 1.35V (Low Voltage)

Operating at 1.5V (normal) and 1.35V (low voltage) and with a transfer speed of up to 1866 MT/s, ATP DDR3 modules deliver better performance while consuming significantly less power than DDR2 memory. ATP DDR3 modules are supported by the Intel® Core™ i7 Series, the AMD AM3 Phenom™ processor, and the latest AMD Embedded Enterprise Chipsets. DDR3 modules are not pin-compatible with the prior-generation modules and have alignment notches preventing them from being inserted into incompatible slots.

ATP offers DDR3 SDRAMs in a wide range of form factors and features including SO-DIMM and Mini-DIMM with low profile, very low profile (VLP) and ultra-low profile (ULP) options.

In addition to standard offerings, ATP's DDR3 product line has enhanced reliability options such as conformal coating for protection against dust, chemicals, extreme temperatures and corrosion. The 30μ" thickness of the gold finger plating ensures better durability and signal transmission quality.

| Technologies | 30μ" Golden Finger | ATP TDBI | Wide Temperature | Anti-Sulfur Resistors | Conformal Coating | PCB Chamfer |
|-----------------|--------------------|----------|------------------|-----------------------|-------------------|-------------|
| ECC UDIMM | ● | ● | ▲ | ▲ | ▲ | ▲ |
| Non-ECC UDIMM | ● | ● | ▲ | ▲ | ▲ | ▲ |
| ECC SO-DIMM | ● | ● | ▲ | ▲ | ▲ | ▲ |
| Non-ECC SO-DIMM | ● | ● | ▲ | ▲ | ▲ | ▲ |
| Mini-UDIMM | ● | ● | ▲ | ▲ | - | - |

▲: Optional

Specifications

| DDR3 | | | | | |
|-----------------------|-----------------------------|-------------------|-------------------|-----------------|-------------------------|
| DIMM Type | ECC UDIMM | Non-ECC UDIMM | ECC SO-DIMM | Non-ECC SO-DIMM | Mini-UDIMM |
| Density | 1 GB to 16 GB | | | | 1 GB to 8 GB |
| Speed up to (MT/s) | 1866 | | | | 1600 |
| PCB Height* | Low profile / VLP / ULP | Low profile / VLP | Low profile / ULP | Low profile | Low profile / VLP / ULP |
| Operating Temperature | 0°C to 85°C / -40°C to 85°C | | | | |

* VLP: 0.74", ULP: below 0.74"

| Hot Items Ordering Information | | | | | |
|---|------|-------|--------|-------|----------------|
| SPEED | SIZE | CHIP | HEIGHT | Ranks | P/N |
| Unbuffered Non ECC Module DDR3-1600 | 4 GB | 512x8 | 1.18" | 1 | AQ12P64A8BLK0M |
| Unbuffered Non ECC Module DDR3-1600 | 8 GB | 512x8 | 1.18" | 2 | AQ24P64B8BLK0M |
| Unbuffered Non ECC SO-DIMM DDR3-1600 | 4 GB | 512x8 | 1.18" | 1 | AW12P6438BLK0M |
| Unbuffered Non ECC SO-DIMM DDR3-1600 | 8 GB | 512x8 | 1.18" | 2 | AW24P64F8BLK0M |



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WE BUILD WITH YOU

Product spec and its related information are subject to change without advance notice.

Please refer to www.atpinc.com for latest information

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